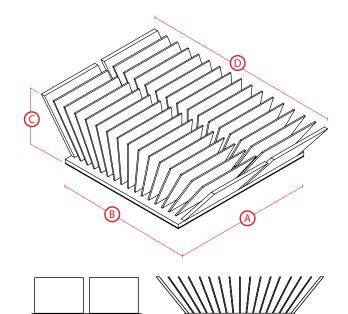


High Performance ASIC Cooling Solutions w/Thermal Tape Attachment

ATS PART # ATS-56010-C4-R0

Features & Benefits

- » maxiFLOW[™] design features a low profile, spread fin array that maximizes surface area for more effective convection (air) cooling
- » Designed specifically for ASIC package and their unique cooling requirements



*Image above is for illustration purposes only.

AIR VELOCITY			THERMAL RESISTANCE				
	FT/MIN	M/S	°C/W (UNDUCTED FLOW)	°C/W (DUCTED FLOW)			
	200	1.0	4	2.3			
	300	1.5	3.3				
	400	2.0	2.6				
	500	2.5	2.3				
	600	3.0	2				
	700	3.5	1.9				
	800	4.0	1.8				

Product Details

Thermal Performance

DIMENSION A	DIMENSION B	DIMENSION C	DIMENSION D	INTERFACE MATERIAL	FINISH
50 mm	45 mm	8.5 mm	66.6 mm	SAINT-GOBAIN NO TIM	BLACK-ANODIZED

NOTES:

1) Dimension C = heat sink height from bottom of the base to the top of the fin field.

2) Thermal performance data are provided for reference only. Actual performance may vary by application.

ATS reserves the right to update or change its products without notice to improve the design or performance.

4) Contact ATS to learn about custom options available.



For more information, to find a distributor or to place an order, visit www.qats.com or call: 781.769.2800 (North America); +31 (0) 3569 84715 (Europe).